

Amendments to the Claims

The following listing of claims will replace all prior versions and listings of claims in the application.

1. (Withdrawn): A fan structure comprising a hub, a motor located inside the hub, a plurality of fan blades connected to the hub, and a circuit board connected to the motor, wherein the circuit board comprises:

a circuit region provided on a first surface of the circuit board, the circuit region comprising at least one heat-generating component thereon; and
a heat-dissipative film coated on an edge portion of the first surface and in contact with the heat-generating component.

2. (Withdrawn): The fan structure as claimed in claim 1, wherein the circuit region is surrounded by the heat-dissipative film.

3. (Withdrawn): The fan structure as claimed in claim 1, wherein the heat-dissipative film extends outside the circumference of the hub.

4. (Withdrawn): The fan structure as claimed in claim 1, wherein the heat-dissipative film is formed with a plurality of openings.

5. (Withdrawn): The fan structure as claimed in claim 1, further comprising a heat sink located on a second surface of the circuit board opposite to the first surface of the circuit board.

6. (Withdrawn): The fan structure as claimed in claim 5, wherein the heat sink is connected to the heat-dissipative film by means of a plurality of through holes and a fastening portion.

7. (Withdrawn): The fan structure as claimed in claim 1, wherein the first surface of the circuit board comprises a protrusion for carrying the heat-generating component and optionally the heat-dissipative film, and the protrusion extends outside the circumference of the hub.

8. (Withdrawn): The fan structure as claimed in claim 7, wherein the protrusion has a cutout that extends from a tip of the protrusion to the heat-generating component.

9. (Withdrawn): The fan structure as claimed in claim 7, wherein the protrusion has a cutout that extends over a portion of the heat-generating component so that the portion of the heat-generating component is exposed via the cutout in the protrusion.

10. (Currently amended): A fan structure comprising a hub, a motor located inside the hub, a plurality of fan blades connected to the hub, and a circuit board connected to the motor, wherein the circuit board comprises a protrusion, which extends outside the circumference of the hub and carries thereon a heat-generating component, and the protrusion comprises a cutout that extends from a tip of the protrusion to the heat-generating component.

11. (Cancelled)

12. (Withdrawn): A circuit board for operating a fan, comprising:
a circuit region provided on a first surface of the circuit board and
including at least one heat-generating component thereon; and
a heat-dissipative film coated on an edge portion of the first surface
and in contact with the heat-generating component.

13. (Withdrawn): The circuit board as claimed in claim 12, wherein the
circuit region is surrounded by the heat-dissipative film.

14. (Withdrawn): The circuit board as claimed in claim 12, wherein the
heat-dissipative film is formed with a plurality of openings.

15. (Withdrawn): The circuit board as claimed in claim 12, further
comprising a heat sink provided on a second surface of the circuit board
opposite to the first surface of the circuit board.

16. (Withdrawn): The circuit board as claimed in claim 15, wherein the
heat sink is connected to the heat-dissipative film by means of a plurality of
through holes and a fastening portion.

17. (Withdrawn): The circuit board as claimed in claim 15, wherein the
heat sink is selected from the group consisting of a heat-conducting film and a
heat-conducting sheet.

18. (Withdrawn): The circuit board as claimed in claim 12, wherein the

first surface of the circuit board comprises a protrusion and the at least one heat-generating component is mounted over the protrusion of the first surface.

19. (Withdrawn): The circuit board as claimed in claim 17, wherein the protrusion has a cutout that extends from a tip of the protrusion to the heat-generating component and optionally to the heat-dissipative film.

20. (Withdrawn): The circuit board as claimed in claim 12, wherein the heat-dissipative film is formed by a coating film made of heat-conducting material.